COBP PHOTO REFLECTOR

**GENERAL DESCRIPTION**

The NJL5901R-2 is the compact surface mount type photo reflector, which is permitted the Lead(Pb)-free reflow soldering (260°C, 2 Times). The NJL5901R-2 has realized the compact package compared with conventional product/NJL5901AR-1.

**FEATURES**

- Miniature, thin package: 1.0mm \( \times \) 1.4mm \( \times \) 0.6mm
- Pb free solder re-flowing permitted: 260°C, 2times
- Built-in visible light cut-off filter

**APPLICATIONS**

- Detecting the location of Lens unit for Cellular Phone’s camera module
- Detecting the watch hand for radio controlled watch
- Detecting the location of CD/DVD optical pickup head
- Detecting the rotation of various motors
- Paper edge detection and mechanism timing detection of facsimile, copy machine etc

**ABSOLUTE MAXIMUM RATINGS (Ta=25°C)**

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>SYMBOL</th>
<th>RATINGS</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Emitter</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Forward Current (Continuous)</td>
<td>IF</td>
<td>20</td>
<td>mA</td>
</tr>
<tr>
<td>Reverse Voltage (Continuous)</td>
<td>VR</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Power Dissipation</td>
<td>PD</td>
<td>45</td>
<td>mW</td>
</tr>
<tr>
<td>Detector</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Collector-Emitter Voltage</td>
<td>VCEO</td>
<td>16</td>
<td>V</td>
</tr>
<tr>
<td>Emitter-Collector Voltage</td>
<td>VECO</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Collector Current</td>
<td>IC</td>
<td>10</td>
<td>mA</td>
</tr>
<tr>
<td>Collector Power Dissipation</td>
<td>PC</td>
<td>25</td>
<td>mW</td>
</tr>
<tr>
<td>Coupled</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Total Power Dissipation</td>
<td>Ptot</td>
<td>60</td>
<td>mW</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>ToPr</td>
<td>-30 to +85</td>
<td>°C</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>Tstg</td>
<td>-40 to +100</td>
<td>°C</td>
</tr>
<tr>
<td>Reflow Soldering Temperature</td>
<td>Tsol</td>
<td>260</td>
<td>°C</td>
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</tbody>
</table>

**ELECTRO-OPTICAL CHARACTERISTICS (Ta=25°C)**

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>SYMBOL</th>
<th>TEST CONDITION</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Emitter</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Forward Voltage</td>
<td>VF</td>
<td>IF=4mA</td>
<td>0.9</td>
<td></td>
<td>1.3</td>
<td>V</td>
</tr>
<tr>
<td>Reverse Current</td>
<td>IR</td>
<td>V=6V</td>
<td></td>
<td>10</td>
<td></td>
<td>μA</td>
</tr>
<tr>
<td>Capacitance</td>
<td>Ct</td>
<td>VR=0V,f=1MHz</td>
<td></td>
<td>25</td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Detector</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Dark Current</td>
<td>ICEO</td>
<td>VCE=10V</td>
<td></td>
<td></td>
<td>0.2</td>
<td>μA</td>
</tr>
<tr>
<td>Collector-Emitter Voltage</td>
<td>VCEO</td>
<td>I=100μA</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Coupled</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Output Current*1</td>
<td>IO</td>
<td>IF=4mA,VCE=2V,d=0.7mm</td>
<td>165</td>
<td></td>
<td>412</td>
<td>μA</td>
</tr>
<tr>
<td>Operating Dark Current *2</td>
<td>ICEOD</td>
<td>IF=4mA,VCE=2V</td>
<td></td>
<td>5</td>
<td></td>
<td>μA</td>
</tr>
<tr>
<td>Rise Time</td>
<td>tr</td>
<td>I=100μA,VCE=2V,RL=1kΩ,d=0.7mm</td>
<td></td>
<td>20</td>
<td></td>
<td>μs</td>
</tr>
<tr>
<td>Fall Time</td>
<td>tf</td>
<td>I=100μA,VCE=2V,RL=1kΩ,d=0.7mm</td>
<td></td>
<td>20</td>
<td></td>
<td>μs</td>
</tr>
</tbody>
</table>

*1 Refer to OUTPUT CURRENT TEST CONDITION

*2 ICEOD may increase according to the periphery situation of the surface mounted product.
OUTLINE (typ.)

OUTLINE (typ.)

OUTPUT CURRENT TEST CONDITION

The infrared signal from LED is reflected at the aluminum surface

DARK CURRENT TEST CONDITION

Light Sealed Dark Box

Aluminum Evaporation Surface

PCB Pattern

A: Anode
K: Cathode
C: Collector
E: Emitter
**RESPONSE TIME TEST CONDITION**

- **INPUT**
- **OUTPUT**
- **R₀**
- **R_L**
- **V_CC**

**EDGE RESPONSE TEST CONDITION**

- **Direction X**
- **Direction Y**
- **Aluminum Evaporation Surface**
- **l=0mm**
- **0.7mm**
TYPICAL CHARACTERISTICS

Power Dissipation vs. Temperature

Forward Current vs. Temperature

Forward Voltage vs. Forward Current

Forward Voltage vs. Temperature

Dark Current vs. Temperature

Operating Dark Current vs. Temperature
Output Current vs. Forward Current (Ta=25°C)

Output Current vs. Temperature

Output Characteristics (Ta=25°C)

Vce Saturation (Ta=25°C)

Output Current vs. Distance (Ta=25°C)

Output Current vs. Edge Distance (Ta=25°C)

IF=4mA, VCE=2V, d=0.7mm

IF=4mA, VCE=2V

IF=2mA

IF=6mA

IF=8mA

IF=10mA
Attention: Please be aware that all data in the graph are just for reference and not for guarantee.
■ MOUNTING METHOD

NOTE
Mounting was evaluated with the following profiles in our company, so there was no problem. However, confirm mounting by the condition of your company beforehand.

Mounting: Twice soldering is allowed.

■ INFRARED REFLOW SOLDERING METHOD

Recommended reflow soldering procedure

![Temperature Profile Diagram](image)

- **a**: Temperature ramping rate : 1 to 4°C/s
- **b**: Pre-heating temperature time : 150 to 180°C : 60 to 120s
- **c**: Temperature ramping rate : 1 to 4°C/s
- **d**: 220°C or higher time : Shorter than 60s
- **e**: 230°C or higher time : Shorter than 40s
- **f**: Peak temperature : Lower than 260°C
- **g**: Temperature ramping rate : 1 to 6°C/s

The temperature of the surface of mold package

(Note1) Using reflow furnace with short wave infrared radiation heater such as halogen lamp
Regarding temperature profile, please refer to those for reflow furnace.
In this case the resin surface temperature may become higher than lead terminals due to endothermic ally of black colored mold resin. Therefore, please avoid from direct exposure to mold resin.

(Note2) Other method
Such other methods of soldering as dipping the device into melted solder and vapor phase method (VPS) are not appropriate because the body of device will be heated rapidly. Therefore, these are not recommended to apply.

(Note3) The resin gets softened right after soldering, so, the following care has to be taken
Not to contact the lens surface to anything.
Not to dip the device into water or any solvents.

■ FLOE SOLDERING METHOD

Flow soldering is not possible.

■ IRON SOLDERING METHOD

Iron soldering is not possible.
■ CLEANING
Avid washing the device after soldering by reflow method.

■ IC STORAGE CONDITIONS AND ITS DURATION
(1) Temperature and humidity ranges

<table>
<thead>
<tr>
<th></th>
<th>Temperature:</th>
<th>Humidity:</th>
</tr>
</thead>
<tbody>
<tr>
<td>Pack Sealing</td>
<td>5 to 40 °C</td>
<td>40 to 80 %</td>
</tr>
<tr>
<td>Pack Opening</td>
<td>5 to 30 °C</td>
<td>40 to 70 %</td>
</tr>
</tbody>
</table>

After opening the bag, solder products within 48h.
Avoid a dry environment below 40% because the products are easily damageable by the electrical discharge.
Store the products in the place where it does not create dew with the products due to a sudden change in temperature.

(2) When baking, place the reel vertically to avoid load to the side.
(3) Do not store the devices in corrosive-gas atmosphere.
(4) Do not store the devices in a dusty place.
(5) Do not expose the devices to direct rays of the sun.
(6) Do not allow external forces or loads to be applied to IC’s.
(7) BE careful because affixed label on the reel might be peeled off when baking.

■ BAKING
In case of keeping expect above condition be sure to apply baking. (Heat-resistant tape)
Baking method:  
Ta=60°C, 48 to 72h, Three times baking is allowed  
Ta=100°C, 2 to 6h, Three times baking is allowed

■ STORAGE DURATION
Within a year after delivering this device.
For the products stored longer than a year, confirm their terminals and solderability before they are used.

■ MOISTURE SENSITIVITY LEVELS
JEDEC : Level 5

■ APPLICATION NOTES
(1) Attention in handling
Treat not to touch the lens surface.
Avoid dust and any other foreign materials on the lens surface such as point, bonding material, etc.
Never to apply reverse voltage (VEC) of more than 6V on the photo transistor when measuring the characteristics or adjusting the system. If applied, it causes to lower the sensitivity.
When mounting, special care has to be taken on the mounting position and tilting of the device because it is very important to place the device to the optimum position to the object.

(2) Attention in designing
Avoid the entering ambient light into light receiving part for avoid the malfunction by ambient light. Furthermore, there is possibility of malfunction when there are the other mounted parts by near this product peripheral.
There will be changing characteristics by detection object. Refer to this datasheet and evaluate by actual detection object.
When LED has been applied continuous power on long period of time, the output current is dropped. If it uses by always applying power to LED, have to consider the circuit designing of including output current decrease.
PACKING SPECIFICATION

PACKING DIMENSIONS  UNIT : mm

Drawing direction

Insert direction

* Carrier tape material : Polycarbonate(antistatic)
Cover tape material : Polyester(antistatic)

Taping Strength
Pull up the cover tape from the carrier tape, and when the opening angle comes around 10 to 15°, and the peeling-off strength is to be within the power of 20 to 70g.

Packaging
1) The taped products are to be rolled up on the taping reel as on the drawing.
2) Rolling up specification
   2-1) Start rolling  : Carrier tape open space more than 20 Pieces.
   2-2) End of rolling : Carrier tape open space more than 20 Pieces, and 2 round of reel space at the cover tape only.
3) Taping quantity  : 2,000 Pieces
4) Seal off after putting each reels in a damp proof bag with silica gel.

[CAUTION]
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